

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. **(Previously Presented)** An electroplating solution for copper comprising $\text{CuSO}_4 \cdot 5\text{H}_2\text{O}$, H_2SO_4 , HCl, polyethylene glycol with a molecular weight greater than 200, hydroxyl amine sulfate, and hydroxyl amine chloride.

2. **(Currently Amended)** A An electroplating solution according to claim 1 further comprising Cl^- ions in a range of 50 – 150 ppm and wherein the hydroxyl amine sulfate is in a range of 0.01 – 5 g/l.

3. **(Currently Amended)** A An electroplating solution according to claim 1 further comprising Cl^- ions derived at least from the HCl in a range of 55 – 125 ppm.

4. **(Previously Presented)** An electroplating solution according to claim 1, further comprising an additive.

5. **(Currently Amended)** A solution according to claim 4, wherein the additive is thiourea, molasses, glucose, tribenzylamine, benzotriazole, or naphthalene sulfonic acid, ~~or~~ $(\text{NH}_2\text{OH})_2 \cdot \text{H}_2\text{SO}_4$.

6. (Currently Amended) An electroplating solution ~~made by comprising~~ adding together:

$\text{CuSO}_4 \cdot 5\text{H}_2\text{O}$;

H_2SO_4 ;

HCl , ~~and~~;

optionally an additive; and

polyethylene glycol with a molecular weight greater than 200, and either hydroxyl amine sulfate or hydroxyl amine chloride.

7. (Currently Amended) An electroplating solution comprising:

$\text{CuSO}_4 \cdot 5\text{H}_2\text{O}$;

H_2SO_4 ;

Cl^- ions, ~~and~~;

polyethylene glycol with a molecular weight greater than 200; and

hydroxyl amine sulfate or hydroxyl amine chloride.

8. (Currently Amended) An electroplating solution according to claim 7, wherein the concentration of ~~$\text{CuSO}_4 \cdot 5\text{H}_2\text{O}$~~ $\text{CuSO}_4 \cdot 5\text{H}_2\text{O}$ is 60 – 150 g/l, H_2SO_4 is 80 – 150 g/l, Cl^- ions are 50 – 150 ppm, and polyethylene glycol is less than 100 ppm, ~~and optionally an additive.~~

9. (Canceled)